

Product Data Sheet Type: **PR8/6,3/SE**

Group: HEATSINKS Board Level

For single mounting

Width : 18.9 mm
 Height : 4.8 mm
 Length : 6.3 mm
 Minimum thermal resistance : 50 K/W
 For device : DIL
 Device mounted by : Bonding
 Heatsink mounted by : Adhesive Bonding
 Surface : Black Anodised
 Material : AlMgSi0,5



- Extruded heatsinks especially for IC's in DUAL IN LINE case.
- Mounting by single component thermal conductive adhesive type WK 709.
- Standard length:
 - 6,3 mm for 14/16 pins
 - 33 mm for 24 pins
 - 37 mm for 28 pins
 - 47 mm for 35 pins
 - 51 mm for 40 pins
- Other lengths and machining on request.

